

IN THE CLAIMS:

Please note that, pursuant to 37 CFR 1.121(c)(3), all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity and for the convenience of the Patent Office. Also attached is a version with markings to show changes made to the claims.

Please amend claims 21, 22, 30 and 34 as set forth below.

*Sub E* 19. (Previously Twice Amended) A method of fabricating a multi-die assembly, comprising  
providing a substrate including a plurality of conductors;  
attaching at least one active face-down base die to said substrate in electrical communication with at least some of said plurality of conductors;  
D securing the back side of at least one active face-up stack die to said at least one base die with electrically conductive adhesive;  
electrically connecting said at least one stack die to at least one of said conductors; and  
electrically grounding said at least one base die via said electrically conductive adhesive and said at least one stack die.

21. (Three Times Amended) The method of claim 19, further comprising:  
securing at least one discrete component to at least one of said at least one stack die, said at least one base die, and said substrate;  
electrically connecting said at least one discrete component to at least one of said stack die, said base die, and said substrate; and  
extending a die-to-component bond wire between said at least one stack die and said at least one discrete component.

22. (Three Times Amended) The method of claim 21, further comprising:

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extending a component-to-substrate bond wire between said at least one discrete component and at least one of said plurality of substrate conductors.

23. (Previously Twice Amended) The method of claim 19, further comprising:  
securing at least another stack die to said assembly; and  
electrically connecting said at least another stack die and at least one of said plurality of substrate conductors.

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25. (Previously Amended) The method of claim 23, further comprising securing said at least another stack die to said at least one stack die.

26. (Previously Twice Amended) The method of claim 25, further comprising:  
securing at least one discrete component to said at least one stack die; and  
extending a die-to-component bond wire between said at least another stack die and said at least one discrete component.

27. (Previously Twice Amended) The method of claim 25, further comprising:  
securing at least one discrete component to said at least one stack die; and  
extending a component-to-substrate bond wire between said at least one discrete component and at least one of said plurality of substrate conductors.

28. (Previously Twice Amended) The method of claim 25, further comprising:  
securing at least one discrete component to said at least one base die; and  
extending a die-to-component bond wire between said at least another stack die and said at least one discrete component.

29. (Previously Twice Amended) The method of claim 25, further comprising:

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securing at least one discrete component to said at least one base die; and  
extending a component-to-substrate bond wire between said at least one discrete component and  
at least one of said plurality of substrate conductors.

30. (Three Times Amended) The method of claim 19, wherein the attaching at least one active face-down base die includes attaching at least two active face-down base die to said substrate and electrically coupling each of said at least two base die with at least one of said plurality of substrate conductors.

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31. (Previously Amended) The method of claim 30, further comprising bridging said at least one stack die between said at least two base die.

32. (Previously Amended) The method of claim 31, further comprising securing at least another stack die over said at least one stack die.

33. (Previously Amended) The method of claim 19, further comprising:  
securing at least one discrete component to said substrate; and  
extending a die-to-component bond wire between said at least one stack die and said at least one discrete component.

34. (Three Times Amended) The method of claim 33, further comprising:  
securing at least another discrete component to said substrate; and  
extending a die-to-component bond wire between said at least one stack die and said at least another discrete component.